# LBI-38975D

# MAINTENANCE MANUAL RADIO FRONT ASSEMBLY 19D902177G17 CONVENTIONAL 19D902177G18 CONVENTIONAL/DTMF

TABLE OF CONTENTS	
	Page
DESCRIPTION	1
FRONT CAP ASSEMBLY	
AUDIO/LOGIC BOARD	
CIRCUIT ANALYSIS	
FRONT CAP ASSEMBLY	
AUDIO/LOGIC BOARD	
ASSEMBLY DIAGRAM	
IC DATA	,
PARTS LIST	
PRODUCTION CHANGES	
OUTLINE DIAGRAM	
LCD BOARD	
SPUR FILTER BOARD	
SCAN/DTMF BOARD	
AUDIO/LOGIC BOARD	
SCHEMATIC DIAGRAM	
FRONT CAP ASSEMBLY	
SCAN/DTMF BOARD	
SPUR FILTER BOARD	
SPUR FILIER DUARD	22
ILLUSTRATIONS	
Figure 1 - Radio Front Assembly	
Figure 2 - Microprocessor Block Diagram	
Figure 3 - Audio Paths Block Diagram	
Figure 4 - Touch-Tone Keypad Frequency Format	
Figure 5 - Audio Response Curve	
Figure 6 - Voltage Waveforms	
Figure 7 - Alert Tones	
Figure 8 - RX Squelch Operation	
Figure 9 - RX Channel Guard Operation	
Figure 10 - RX Type 99 Operation	
Figure 11 - TX Voice-Only Operation	/
Figure 12 - TX Channel Guard Operation	/

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# ERICSSON 💋

Printed in U.S.A.

# DESCRIPTION

The Radio Front Assembly (19D902177G17) for the PCS Portable Synthesized radio consists of the following components:

- Front Cap Assembly 19D902180G10
- Audio/Logic Board 19D902631G2
- Metal Over Elastomer (MOE) Connector 19A705662P1 and Holder 19B801570P2

The Radio Front Assembly (19D902177G18) for the PCS SCAN/DTMF Portable Synthesized radio consists of the following components:

- Front Cap Assembly 19D902180G11
- Audio/Logic Board 19D902631G2 •
- Metal Over Elastomer (MOE) Connector 19A705662P1 and Holder 19B801570P2

The front cap assembly consists of a LEXAN front housing, a control assembly, and a speaker.

The control assembly houses most operator switches/buttons, the Liquid Crystal Display (LCD), and the microphone. The Metal Over Elastomer (MOE) connector provides the interface between the printed runs on the control assembly and the printed runs on the Audio/Logic board.

The front housing contains the SCAN board (G17) or the SCAN/DTMF board that mounts the DTMF Pad (G18).

### - NOTE

All references to the SCAN function, equipment and accessories apply only to the 8- and 16-channel radios.

#### FRONT CAP ASSEMBLY

Front cap assembly 19D902180G10 consists of a molded plastic circuit board (control frame), a Liquid Crystal Display (LCD) assembly, switches/buttons for the basic radio functions, and a Universal (User) Device Connector (UDC) all mounted in a plastic front housing.

Front cap assembly 19D902180G11 consists of a molded plastic circuit board (control frame), a Liquid Crystal Display (LCD) assembly, switches/buttons for the basic radio functions, and a Universal (User) Device Connector (UDC), all mounted in a plastic front housing. A DTMF keypad board is also mounted to the front housing. A SCAN/DTMF cable assembly connects this board to the Audio/Logic board.

The assembly diagram shows both a pictorial view of the control assembly and a view of the control assembly mounted into the radio front housing. The control frame acts like a three-dimensional printed circuit board.

The base material consists of "ULTEM" molded plastic with a two-layer printed circuit pattern on the outside perimeter of the frame. The control frame interfaces with the following:

- Control Switches/Buttons •
- Liquid Crystal Display Module (LCD)
- Microphone
- Speaker
- User (Universal) Device Connector (UDC)

#### **AUDIO/LOGIC BOARD**

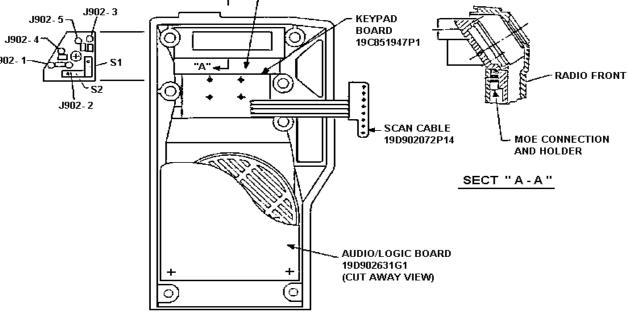
Audio/Logic board 19D902631G2 mounts in the Front Cap Assembly as shown in Figure 1. All Front Cap control switch operations are connected to the Audio/Logic board through MOE interface connector. The SCAN push-button board is connected by a cable to J802 on the Audio/Logic board.

A microprocessor on the Audio/Logic board interprets these commands and issues commands to the Audio/Logic circuits, the RF circuits and the LCD module on the control assembly. Microphone and speaker audio is also transferred through the MOE connector.

Refer to Figure 2 for a block diagram of the microprocessor and associated circuitry and to Figure 3 for a block diagram of the audio paths (see Table of Contents).

The Audio/Logic board consists primarily of the following:

- Microprocessor
- EEPROM
- RX Audio Processing
- TX Audio Processing
- Regulators and Special Circuits •



#### REAR VIEW

"A" 🔶

Figure 1 - Radio Front Assembly

**CIRCUIT ANALYSIS** 

#### FRONT CAP ASSEMBLY

#### **Control Switches/Buttons**

The control switches/buttons include the PTT, MONitor, CHANnel UP/DOWN, and VOLume UP/DOWN controls. A "dome" switch pad adheres to the control frame with domed metal switches. When pressed, these switches make direct contact with runs on the control frame. A rubber keypad fits over the switch assembly for operator interface and weather protection.

### **SCAN Switches**

The SCAN push-button switches consist of the ADD/HOME/EMERGENCY/BACKLIGHT, SCAN, and DE-Lete buttons, mounted on a small printed wiring board. Pressing these switches makes contact with the runs on the board. These lines are connected to the Audio/Logic board by a cable that plugs into the Audio/Logic board.

On the Radio Front Assembly (19D902177G18) the SCAN/TALK AROUND and DELete/POWER SET buttons are part of the DTMF keypad.



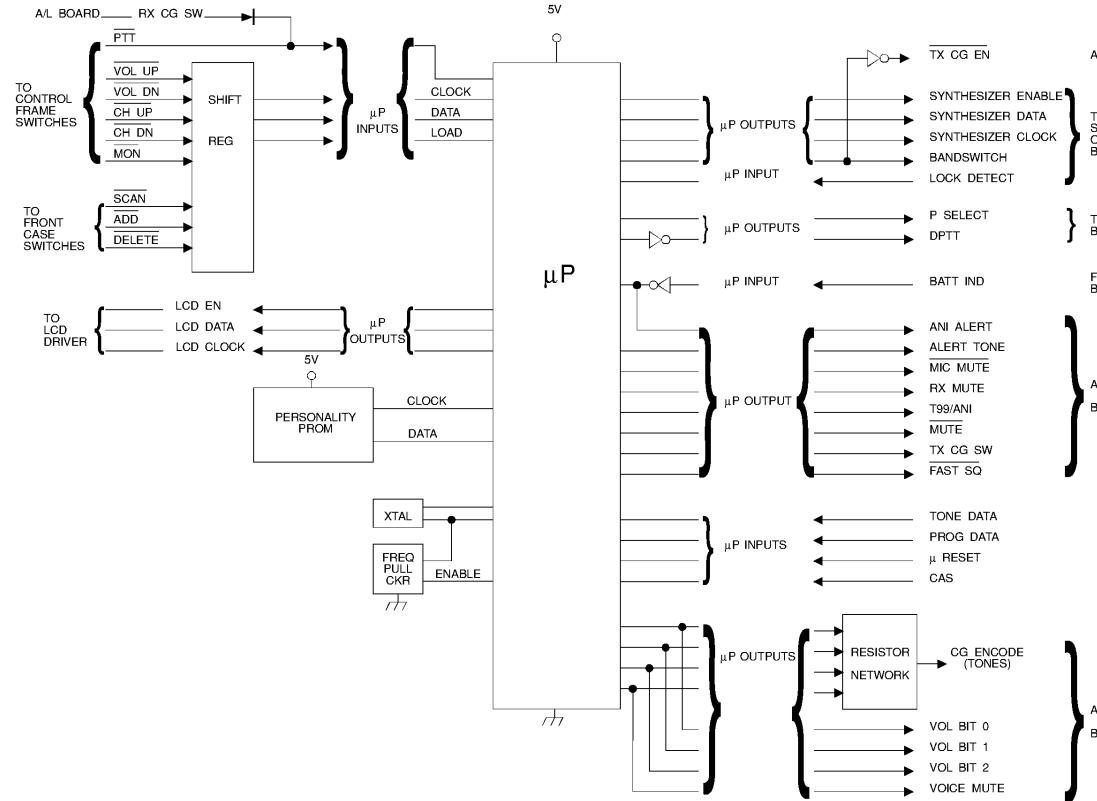


Figure 2 - Microprocessor Block Diagram

### A/L BOARD

TO SYNTHESIZER ON RF BOARD

TO RF BOARD

> FROM RF BOARD

A/L BOARD

A/L BOARD

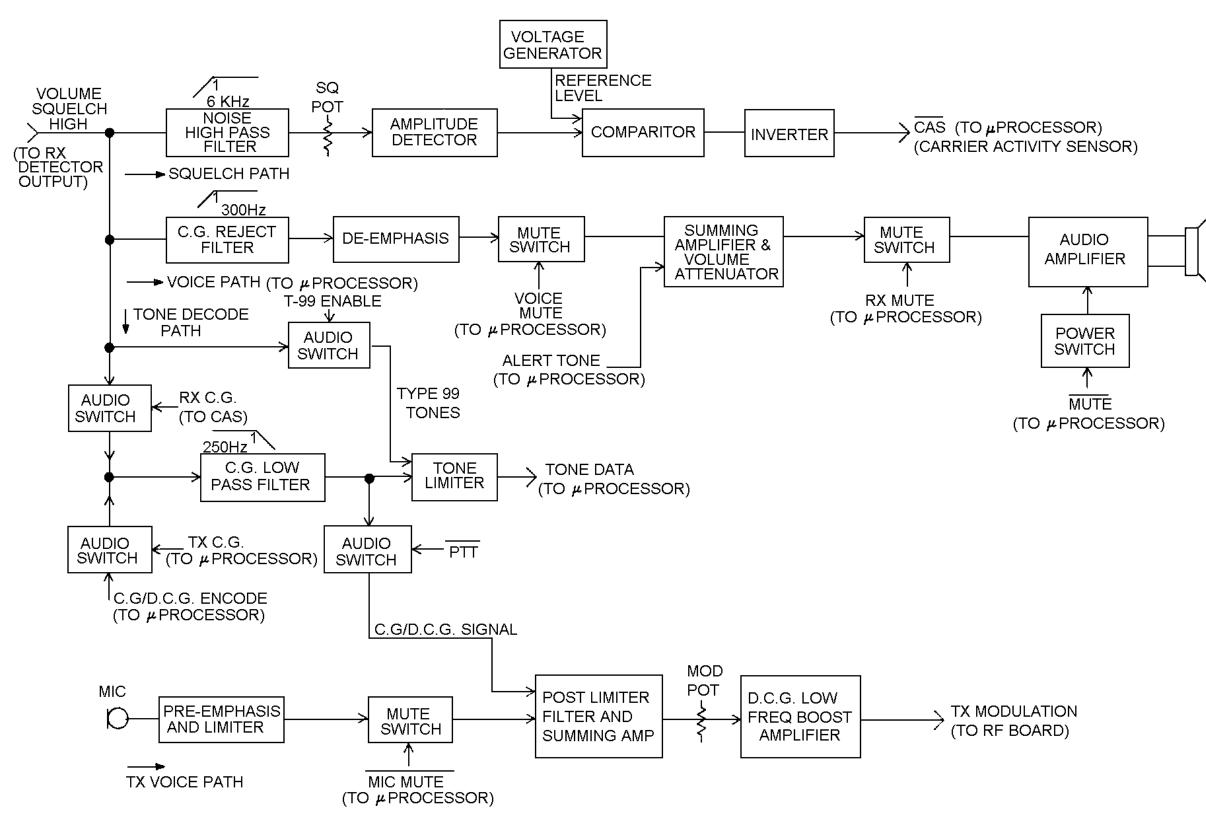


Figure 3 - Audio Paths Block Diagram

### **DTMF Encoder**

The DTMF Encoder is used for encoding PCS personal radios with standard DTMF tones. The encoder consists of two parts: printed circuit board A1 and a twelve-key rubber keypad. The printed circuit board is mounted in the front cap assembly.

- The encoder performs the following functions:
- Generation of DTMF tone frequencies corresponding to digits dialed on the keypad.
- Continuous tone output as long as any digit is • keyed on the keypad.
- Sidetone output to the radio speaker to permit monitoring the tones as they are transmitted.
- Uses standard tone format for high signalling reliability and equipment compatibility.

The DTMF Encoder uses standard dual tone multi-frequency format for telephone dialing. Each digit is identified by a unique combination of two tones; one corresponding to the horizontal row, and the other to the vertical column of push-button positions shown in Figure 4.

The frequencies are grouped about geometric center of the 300 to 3000 Hz voice band used in telephone and radio systems. The two tones are generated simultaneously and remain on as long as a digit on the keypad is being pressed. Row tones are in a lower frequency group than column tones. The frequencies are non-harmonic to give high immunity to false identification from beat frequencies and distortion-produced overtones.

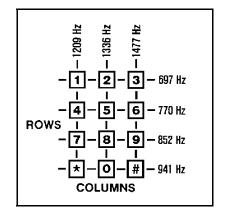


Figure 4 - Touch-Tone Keypad Frequency Format

#### **SCAN/DTMF Board**

The DTMF keypad is disabled until the PTT switch on the side of the radio is pressed and held. The PTT signal keys the microcomputer in the Audio/Logic board, Power and clock are toggled through J802.1 to the SCAN/DTMF microprocessor, enabling the oscillator. As the keypad buttons are pressed, digital signals, representing DTMF tones, are generated by ladder network resistors R8-R13. These

signals pass through the R-C filter (R14-R16 and C3-C5). Side tones are connected to the receive audio section through J802.8 and are then sent to the transmitter modulator through J801.5 (on Audio/Logic board).

#### Liquid Crystal Display

(LCD) consists of LCD driver board A1, a diffuser, two zebra strips, the LCD, and a lens. The LCD assembly is held together by the lens. The primary function of this board is to illuminate LCD segments as controlled by the radio microprocessor on the Audio/Logic board.

Another function of this board is to provide backlighting of the LCD module. This is accomplished by using four LED devices (D1-D4). These LED's are turned on by LCD DAT/LT line and powered by a voltage switching circuit consisting of chip transistors Q1 and Q2. The diffuser, placed immediately above the LED's, evenly distributes the light. The zebra strips connect the driver board to the LCD and the entire assembly plugs into the control frame with six pins.

#### **Microphone and Speaker**

The microphone (B901) mounts directly onto the control frame (HL1 and HL2). The control assembly, when placed into the radio front assembly, is located in the correct position for receiving voice when used. The speaker, mounted i the front housing, connects to the control frame (HL3 and HL4) through two (2) wires. A protective grill cloth is placed on the front housing before the speaker is mounted to screen out foreign material.

#### User (Universal) Device Connector (UDC)

Part of the control frame forms UDC U901 for customer programming and for connecting external options. The speaker leads, mic high, and PTT are all brought to this connector along with ground. The mic lead and one of the speaker leads are switched to the UDC, only when micro switches S1 and S2 are operated. These switches are activated by plungers compatible PCS personal radio options. A rubber boot is placed over this connector for weather protection.

#### **AUDIO/LOGIC BOARD**

#### **Microprocessor (80C52)**

An 8-bit microprocessor (U1) is used to provide all of the control signals required by the radio. The microprocessor also generates Channel Guard tones, Digital Channel Guard words, GE STAR, ANI words, and detects Channel Guard and Type 99 tones.

The microprocessor is located on Spur Filter board (A701). The Spur Filter board includes RC filters on each port of the processor and a metal can soldered on top of the board to reduce the effect of the microprocessor-generated spurious signals.

**Table 1 - Microprocessor Port Pin Identification** 

P0.0 (O) Channel Guard Encode Bit P2.0 (O)

0/Volume Attenuator Bit 0

# **EEPROM**

as:

- Customer frequencies
- Customer tones

Programming of the EEPROM is accomplished by driving the MIC HI lead, which is connected to operational amplifier circuit U302.2. With no external signal connected to MIC HI, a voltage level of 2.1 volts is at MIC HI. This causes the output of U302.2 (the program data line) to be high.

When the MIC HI is pulled low, the program data line is pulled low. If this line remains low for 20 milliseconds or longer, the microprocessor is switched into the programming mode. Once in this mode, the radio will not operate or respond to any front case button. The radio must be turned off and then back on to get the processor out of this mode.

When the microprocessor is programmed, the processor will be taken out of the programming mode by the proper character from the personal computer programmer.

# **RX Audio Processing**

Voice Path

Received audio enters the Audio/Logic board on Pin 10 of J801. Frequencies below 300 Hz are attenuated by the Channel Guard reject filter consisting of U602.1 and associated circuitry.

The output from the CG reject filter is coupled through voice mute switch transistor Q603 to the volume attenuator circuit U602.2, and resistors R632 through R640. The feedback resistors are selected by bilateral switch Q603 and controlled by inputs volume bit 0, 1, and 2. Here the 500 Hz alert tone, generated by the microprocessor, can be added to the received audio at the alert tone input.

The volume attenuator has a range of 48 dB. The attenuator output is coupled through RX MUTE switching transistor Q606 to audio amplifier transistor U604. ANI alert is coupled to U604 input through C608 and R673. Power is supplied to the audio amplifier by transistors Q605 and Q606 and controlled by the MUTE line from the microprocessor. Amplifier U604 drives the speaker with differential outputs, which are also connected to the accessory connector through the control assembly.

#### LCD Data P0.1 (O) Channel Guard Encode Bit P2.1 (O) 1/Volume Attenuator Bit 1 P0.2 (O) Channel Guard Encode Bit P2.2 (O) LCD Clock 2/Volume Attenuator Bit 2 P2.3 (O) P0.3 (O) Channel Guard Encode Bit Receive Mute (active

LCD Enable

	3/Volume Attenuator Bit 3		high)
P0.4 (I)	Low Battery Indication (active low)/ANI Alert	P2.4 (O)	T99/ANI
P0.5 (O)	Transmit Channel Guard Switch (active high)	P2.5 (O)	Synthesizer Clock
P0.6 (O)	Mute (active low)	P2.6 (O)	Synthesizer Data
P0.7 (O)	Delayed PTT (active low)	P2.7 (O)	Synthesizer Data
P1.0 (O)	Fast SQ	RXD (I)	Programmer Data
P1.1 (I)	Load (serial load)	TXD (I/O)	Programmer Data Out/PTT
P1.2 (I)	Clock (serial load)	P3.2 (I)	Tone Data
P1.3 (I)	CAS (active low)	P3.3 (I)	Lock Detect
P1.4 (I)	QH (active low) (serial load)	P3.4 (O)	Alert Tone
P1.5 (O)	XTAL Bit	P3.5 (O)	Band Switch
P1.6 (O)	Mic Mute (active low)	P3.6 (O)	E <sup>2</sup> PROM Clock
P1.7 (O)	Power Select	P3.7 (O)	E <sup>2</sup> PROM Data

Port Pins I=Input O=Output I/O=Bidrectional

The 512 x 8-bit EEPROM (U701), commonly referred to as the personality PROM, stores customer information, such

• Customer options

Using the EEPROM provides the convenience of programming without opening the radio.

A 6 dB/octave de-emphasis is provided by capacitor C615 and resistor R628 in the CG reject filter. Capacitor C622 and resistor R644 provide additional roll-off at higher frequencies.

#### **Squelch Path**

The squelch circuit operates on the noise components contained in the discriminator output. The signal at J801-10 is applied to a high-pass filter consisting of U601.2 and associated circuitry. The output of U601.2 is noise in a band around 6 kHz. The gain of the high-pass filter is determined by squelch potentiometer R608.

The output of U601.2 is rectified by U601.1, resistors R610 through R612, and capacitors C607 and C639. C607 is switched into operation by Q609. The Fast Squelch line, in turn, controls Q609. C607 is always switched into operation during a non-SCAN operation. During SCAN operation, C607 is switched out of the circuit for rapid squelch operation. This DC signal is then applied to comparator U601.4. If the rectified noise is more than 0.20 VDC, the CAS line is high and the microprocessor mutes the audio. Feedback resistor at U601.4 provides about 2 dB of hysteresis. Resistors R614, R662, R663, and thermistor R664 are used for temperature compensation or the threshold level.

The threshold level is temperature compensated at cold temperatures only by thermistor R664. This is necessary because of a drop in the VOL/SQ HI noise level. Thermistor R664 has a negative temperature coefficient. At  $25^{\circ}$  C and above, the thermistor has little effect on the threshold voltage level at U601B, Pin 12. At temperatures below  $25^{\circ}$  C, the resistance increases exponentially, thereby causing a drop in the threshold voltage. This voltage drop approximately tracks the voltage drop at the detected noise terminal, U601.2-13.

#### **Limited Tone Data Path**

Limited Tone Data is the 5 volts (peak-to-peak) representation of a received tone and is fed to the microprocessor where the actual tone decoding occurs. This circuit consists of an amplifier followed by a low-pass filter for voice rejection and a voltage comparator.

The low-pass filter consists of U606.1 and associated circuitry. This filter is used for both Channel Guard encoding and decoding. The filter has a breakpoint at 210 Hz. Type 99 decoding is done by bypassing the low-pass filter and going directly to comparator U606.2.

#### **TX Audio Processing**

Audio from the microphone is applied to a 6 dB/octave pre-emphasis network consisting of capacitor C301 and resistor R306 and then to amplifier U301.1. Amplifier U301.2 provides further gain and symmetrical limiting. The output of U301.2 is coupled through mic mute switch U605.3 to the post-limiter filter consisting of U302.1 and associated circuitry. Transmit Channel Guard tones are added to the microphone audio at the post-limiter filter. GE STAR ANI is also fed into post-limiter filter when programmed.

The transmit signal is applied to the low-frequency boost circuit U303.1, U303.2, and associated circuitry. The transmit deviation is set by MOD potentiometer R3211.

The low-frequency boost circuit provides an increasing output level as the input frequency decreases below 20 Hz. The shape of the response curve is shown in Figure 5. This shape is intended to be the mirror image of the synthesizer frequency response curve. The combined result of these two curves provide relatively flat modulation below 5 Hz. This is necessary for Digital Channel Guard modulation.

#### **Regulator and Special Circuitry**

A +5 volt regulator U802 supplies power to the microprocessor and all other circuitry requiring +5 volts. A voltage divider provides the input to U601.3 to generate a 2,25 volt reference for operational amplifier biasing.

#### Low Voltage Reset

Voltage detector U801 and transistor Q803 provide the microprocessor with the necessary reset signal during the power-up routine as well as resetting the microprocessor when the battery falls below approximately 4.75 volts (see Figure 6).

#### Low Battery Indicator

When the battery voltage drops to approximately 6.3 volts, the BAT IND line from the RF board is sufficiently high to turn on Transistor Q802. The output of Q802, the low battery line, drives a microprocessor port. This action turns on the BAT pixel on the LCD.

#### **User Input**

Control assembly connector J901 and SCAN connector J802 on the Audio/Logic board provide the interface between the operator and the radio. By pressing buttons on the switch panel or SCAN keypad, the operator can:

- Change volume level or channel.
- Monitor a channel.
- Key the transmitter.
- Turn SCAN on or off.
- Add or delete SCAN channels from the Scan list.
- Switch to HOME channel.

All operator commands are applied to an 8-bit shift register U803, which loads the data and control inputs into the micro-processor through J701-3, J701-4, and J701-6.

The LCD is updated to reflect the current status of the radio. The microprocessor configures the LCD through LCD EN (P2.0), LCD DAT (P2.1), and LCD CLK (P2.2).

#### Synthesizer Programming

After a reset, when toggling between transmit and receive, and anytime a new channel is selected, the microprocessor must reprogram the synthesizer through SYN CLK (P2.5), SYN DAT (P2.7), and SYN EN (P2.6). When locked, the LOCK DET line (J9801-11) is high.

#### **Alert Tone**

The microprocessor generates a 500 Hz alert tone (P3.4) used to signal the user of critical events. These events include synthesizer out-of-lock and activation of the volume up, volume down, and channel up buttons. The alert tone can be disabled by the programmer.

#### **Microprocessor XTAL Frequency Pull**

Port P1.5 of the microprocessor is used to switch a 33 pF capacitor (C701) into the crystal oscillator circuit. The effect of adding this capacitor is to move or pull the XTAL frequency approximately 250 ppm. This is done to keep harmonics of the microprocessor ALE line away from the receive channel frequency.

The programming at this point happens automatically when channel frequencies are initially programmed.

# LBI-38975

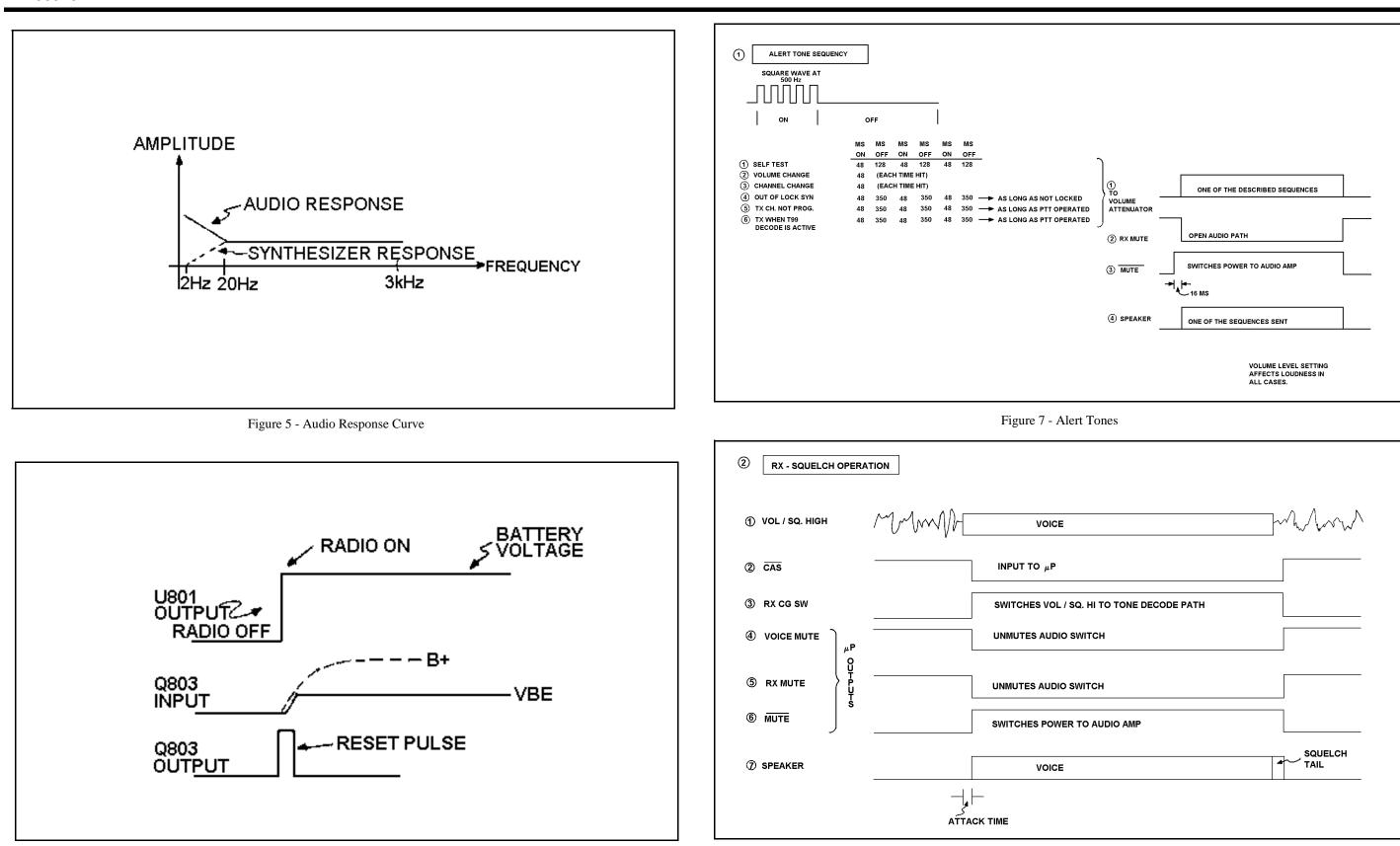


Figure 6 - Voltage Waveforms

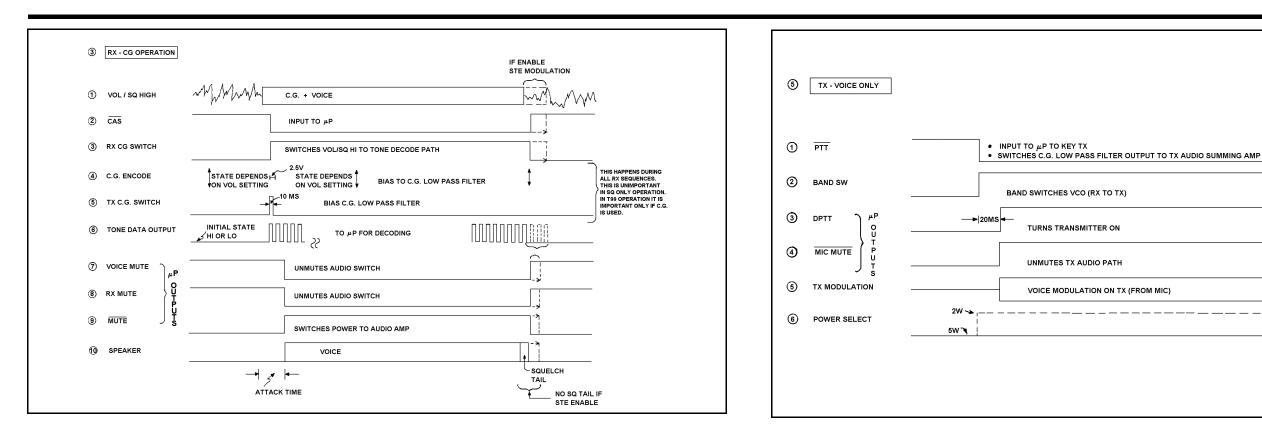


Figure 9 - RX Channel Guard Operation

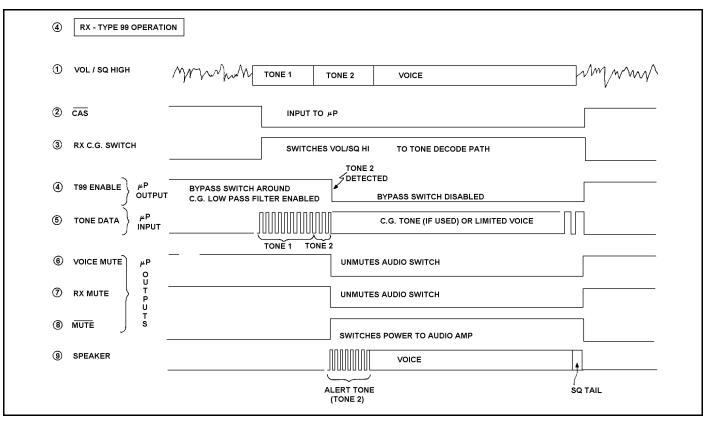


Figure 10 - RX Type 99 Operation

Figure 11 - TX Voice-Only Operation

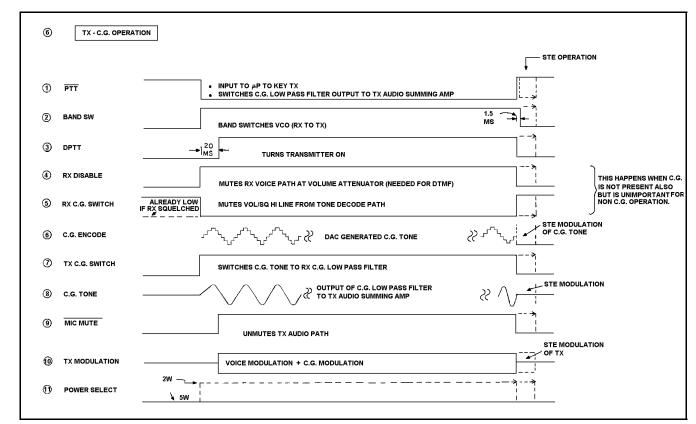
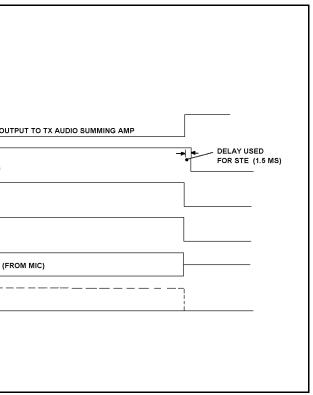
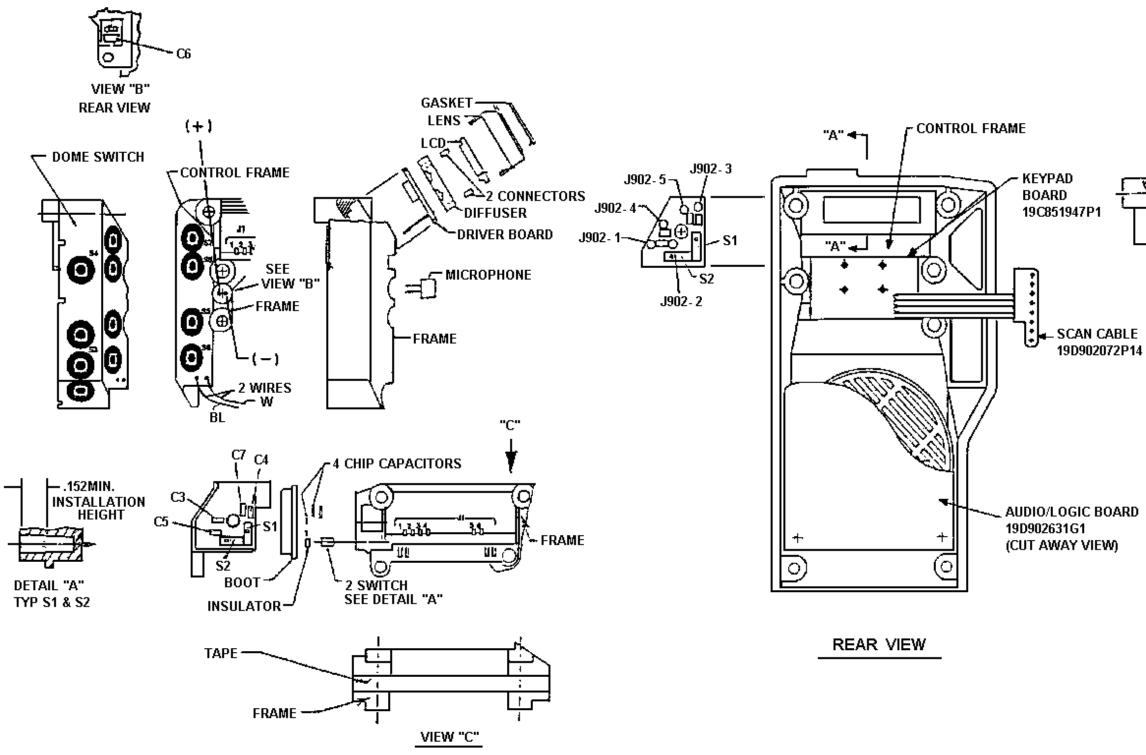


Figure 12 - TX Channel Guard Operation

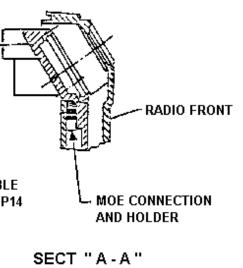
LBI-38975

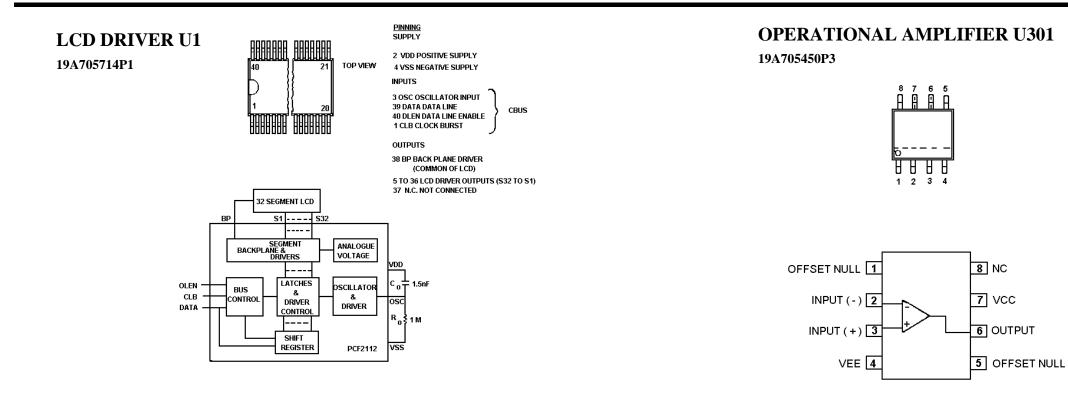




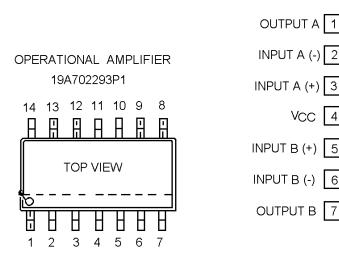
# FRONT CAP ASSEMBLY

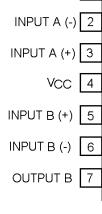
19D902180G10 & G11



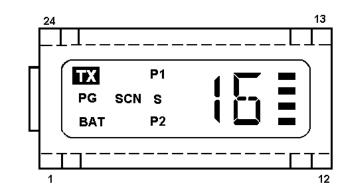


# **OPERATIONAL AMPLIFIER U601** 19A702293P1



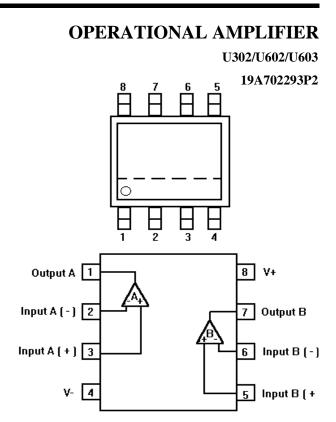


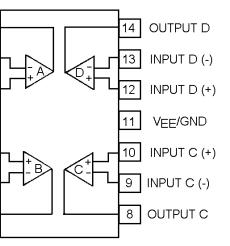




	PIN OUT				
1	COM		13	NC	
2	PG		14	BAR 2	
3	BAT		15	BAR 3	
4	SCN		16	BAR 4	
5	P2		17	1B	
6	ONE		18	1A	
7	1E		19	1F	
8	1D		20	1G	
9	1C		21	P1	
10	BAR 1		22	S	
11	NC		23	ТΧ	
12	COM		24	COM	

# LBI-38975





### PIN 1 MAY BE IDENTIFIED BY INDENT OR CHAMFER

19A702705P3

19A705452P1

OUTPUT

OUTPUT

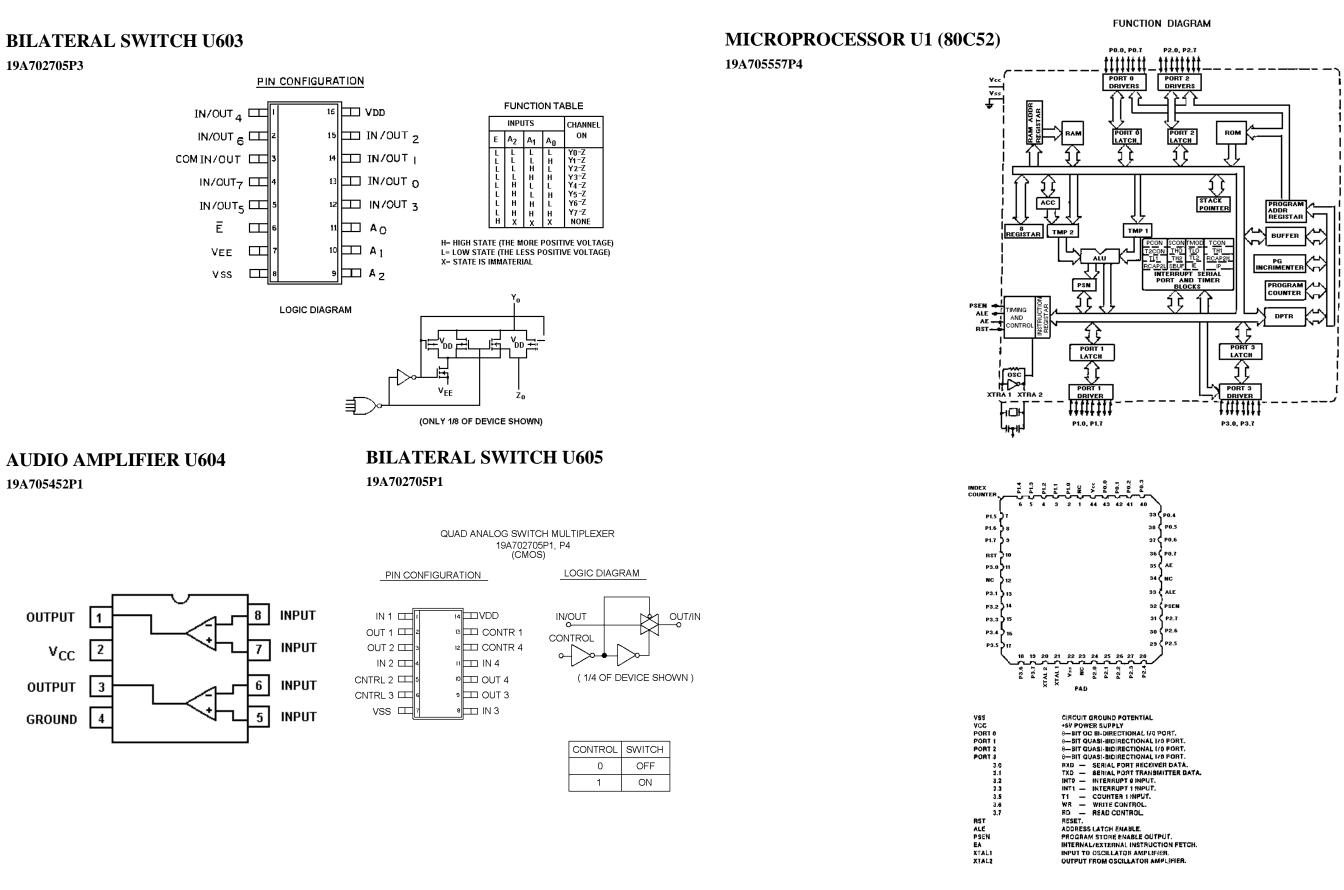
٧<sub>CC</sub>

GROUND 4

2

3

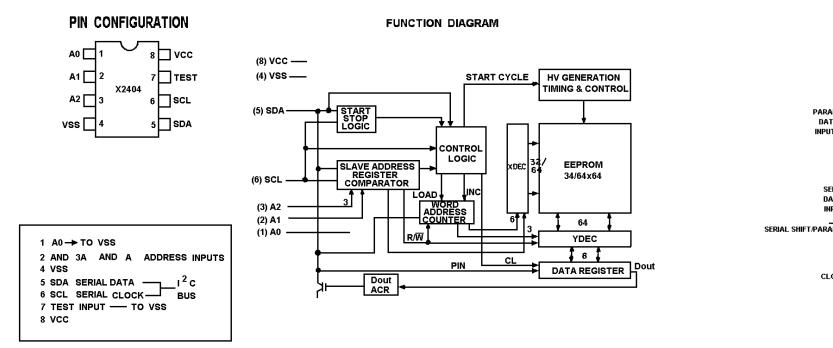
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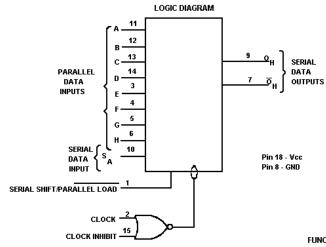


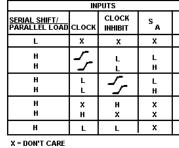
# SHIFT REGISTER U803

#### 19A703987P322

IC DATA







<sup>Q</sup>An<sup>-Q</sup>Gn = DATA SHIFTED FROM PRECEDING STAGE

12

11

сс

сс

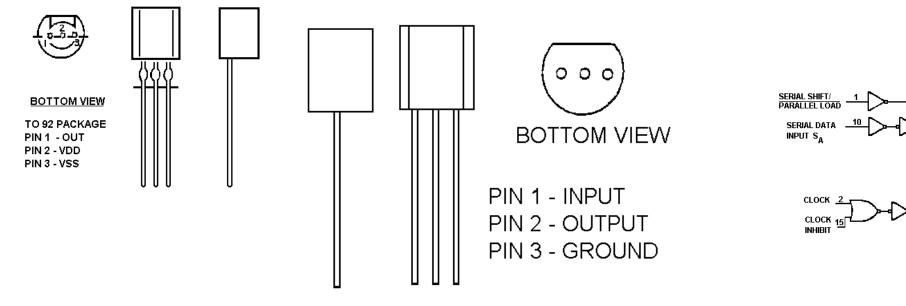
#### EXPANDED LOGIC DIAGRAM

13

ΙI

Q,

сс



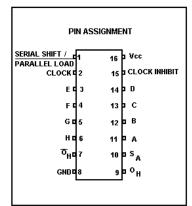
# **EEPROM U701**

### RYT1186070/1

**VOLTAGE DETECTOR U801** 19A705454P1

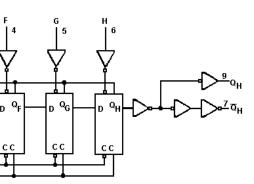
# **VOLTAGE REGULATOR U802** 19A702536P1

# LBI-38975



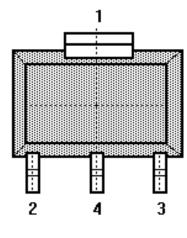
#### FUNCTION TABLE

	INTE	RNAL	AUTOUT	
A H	ST Q <sub>A</sub>	AGES <sup>Q</sup> B	OUTPUT <sup>Q</sup> H	OPERATION
ah	a	b	h	ASYNCHRONOUS PARALLEL LOAD
××	L H	Q <sub>An</sub> Q <sub>An</sub>	Q <sub>Gn</sub>	SERIAL SHIFT VIA CLOCK
x x	L H	Q <sub>An</sub> Q <sub>An</sub>	Q <sub>Gn</sub> Q <sub>Gn</sub>	SERIAL SHIFT VIA CLOCK INHIBIT
××	NO CHANGE		ANGE	INHIBITED CLOCK
x		NO CH	ANGE	NO CLOCK



# **48-BIT SERIAL NUMBER ROM U804**

344A4050P101



TOP VIEW

# PIN NAMES

- Pin 1 Ground
- Pin 2 Data (DQ)
- Pin 3 No Connect

TWO 16-BIT

TIMER/EVENT COUNTERS

PROGRAMMABLE

PROGRAMMABLE SERIAL PORT • FULL DUPLEX UART • SYNCHRONOUS SHIFTER

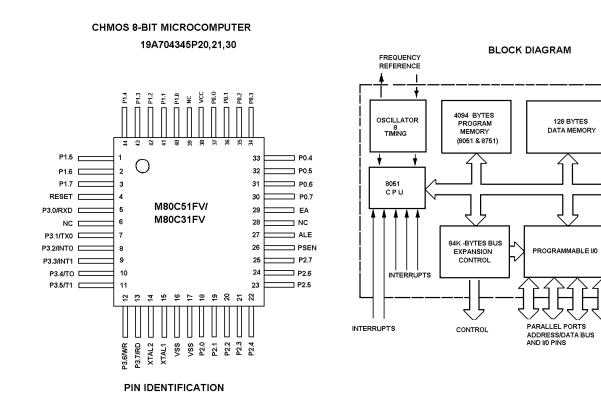
> SERIAL OUT

SERIAL IN

Pin 4 Ground

# MICROPROCESSOR U1 (80C51)

### 19A704345P30



# FRONT CAP ASSEMBLY

(CONVENTIONAL) 19D902177G17

# (CONVENTIONAL/DTMF) 19D902177G18

SYMBOL	PART NO.	DESCRIPTION
A2 A701	19D902631G2 19C851678G4	AUDIO/LOGIC BOARD
A701	19085167864	SPUR FILTER BOARD
		CAPACITORS
C1		
thru C34	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30
001	10/11/02/00/11/00	PPM/°C.
C35	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.
C36	19A702061P35	Ceramic: 30 pF ±5%, 50 VDCW, temp coef 0±30 PPM.
		PLUGS
P701	19B801573P1	Connector.
		RESISTORS
R1	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R2	1300012311 102	
and R3	19B801251P101	Metal film: 100 ohms ±5%, 1/10 w.
R4	1300012311 101	Wetar mm. 100 0mms ±3 %, 1/10 w.
and R5	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R6	19B801251P101	Metal film: 100 ohms $\pm 5\%$ , 1/10 w.
R7		
thru R14	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R15		
thru R17	19B801251P101	Metal film: 100 ohms ±5%, 1/10 w.
R18		
thru R22	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R23		
thru R25	19B801251P471	Metal film: 470 ohms ±5%, 1/10 w.
R26		
thru R30	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R31		
thru R34	19B801251P101	Metal film: 100 ohms ±5%, 1/10 w.
R35	19B801251P220	Metal film: 22 ohms ±5%, 1/10 w.
		INTEGRATED CIRCUITS
U1	349A9595G5	Microcomputer: 8-bit, CHMOS; 8XC524.
01	3497939363	
		CAPACITORS
C301	19A702052P7	Ceramic: 2200 pF ±10%, 50 VDCW.
C302	19A702052P30	Ceramic: $0.022 \mu\text{F} \pm 10\%$ , 50 VDCW.
C303	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0±30 PPM.
C304	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW
C305 C306	19A702052P10 19A705205P2	Ceramic: 4700 pF $\pm$ 10%, 50 VDCW. Tantalum: 1 $\mu$ F, 16 VDCW; sim to Sprague 293D.
C306 C307	19A705205P2 19A702052P107	Ceramic: 2200 pF $\pm$ 5%, 50 VDCW.
C308	19A702052P30	Ceramic: 0.022 µF ±10%, 50 VDCW.
C309	19A702061P67	Ceramic: 180 pF ±5%, 50 VDCW, temp coef 0±30 PPM.
C310	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW
C311	19A702052P30	Ceramic: 0.022 $\mu F$ ±10%, 50 VDCW.
C312 and		
C313	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW
C314	19A702061P73	Ceramic: 330 pF ±5%, 50 VDCW, temp coef 0±30 PPM/°C.
C315		
and C316	19A702052P26	Ceramic: 0.1 µF ±10%, 50 VDCW
C317	19A702052P30	Ceramic: 0.022 µF ±10%, 50 VDCW.
C318 C319	19A702052P26 19A702061P45	Ceramic: 0.1 $\mu$ F ±10%, 50 VDCW Ceramic: 47 pF ±5%, 50 VDCW, temp coef 0±30
0010		PPM.
C601	19A702052P107	Ceramic: 2200 pF ±5%, 50 VDCW.
C602	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0±30 PPM.
C603	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0 ±30
		PPM.

	1	Γ	1		
SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART NO.	DESCRIPTION
C604	19A702052P105	Ceramic: 1000 pF ±5%, 50 VDCW.			TRANSISTORS
C605	19A702052P7	Ceramic: 2200 pF ±10%, 50 VDCW.	Q601		
C606 C607	19A702052P26 19A705205P2	Ceramic: 0.1 $\mu$ F ±10%, 50 VDCW Tantalum: 1 $\mu$ F, 16 VDCW; sim to Sprague 293D.	and Q602	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
C608	19A702061P77	Ceramic: 470 pF $\pm$ 5%, 50 VDCW, temp coef 0 $\pm$ 30	Q603	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.
0000	404700050000	PPM.	Q604	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
C609 C610	19A702052P30 19A702052P10	Ceramic: 0.022 μF ±10%, 50 VDCW. Ceramic: 4700 pF ±10%, 50 VDCW.	Q605 Q606	19A700026P2 19A700059P2	Silicon, PNP: sim to BC369. Silicon, PNP: sim to MMBT3906, low profile.
C611	13/10/20321 10	Ceramic. 4700 pr ±10%, 50 VDCW.	Q607	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.
and C612	19A702052P114		Q608	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
C612 C613	19A702052P114 19A702052P30	Ceramic: 0.01 μF ±5%, 50 VDCW. Ceramic: 0.022 μF ±10%, 50 VDCW.	Q609 Q610	19A700076P2 19A700059P2	Silicon, NPN: sim to MMBT3904, low profile. Silicon, PNP: sim to MMBT3906, low profile.
C614	19A702052P26	Ceramic: $0.1 \mu\text{F} \pm 10\%$ , 50 VDCW	Q610 Q611	19A700059P2 19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
*C615	19A702052P12	Ceramic: 6800 pF ±10%, 50 VDCW.	Q612	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.
C616	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.	Q704 Q706	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
C617 C618	19A702052P5 19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW. Ceramic: 1000 pF ±10%, 50 VDCW.	Q706 Q801	19A700076P2 19A700059P2	Silicon, NPN: sim to MMBT3904, low profile. Silicon, PNP: sim to MMBT3906, low profile.
C619	19A702052P14	Ceramic: $0.01 \ \mu\text{F} \pm 10\%$ , 50 VDCW.	Q802		
C620	19A704879P14	Electrolytic: 68 μF ±20%, 10 VDCW.	thru Q804	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
C621	19A702052P30	Ceramic: 0.022 µF ±10%, 50 VDCW.	4001		
C622	19A702052P30 19A704879P5	Ceramic: 0.022 μF ±10%, 50 VDCW.			RESISTORS
C623 C624	19A704879P5 19A702052P14	Electrolytic: 10 μF ±20%, 16 VDCW. Ceramic: 0.01 μF ±10%, 50 VDCW.	R301	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
C626	10/11/02/00/21 14	Ceramic. 0.01 μι ±10%, 30 VDCW.	R302	19B801251P105	Metal film: 1M ohms ±5%, 1/10 w.
and	404700050000		R303	19B801251P272	Metal film: 2.7K ohms ±5%, 1/10 w.
C627 C628	19A702052P26 19A705205P2	Ceramic: 0.1 $\mu$ F ±10%, 50 VDCW Tantalum: 1 $\mu$ F, 16 VDCW; sim to Sprague 293D.	R304	19B801251P103	Metal film: 10K ohms $\pm 5\%$ , 1/10 w.
C629	13/10320312	ranaium. 1 μr, 10 vDCw, sim to Sprague 293D.	R305 R306	19B801251P102 19B801251P103	Metal film: 1K ohms ±5%, 1/10 w. Metal film: 10K ohms ±5%, 1/10 w.
and	104702052040		R307	19B801251P333	Metal film: 33K ohms ±5%, 1/10 w.
C630 C631	19A702052P10 19A702052P14	Ceramic: 4700 pF ±10%, 50 VDCW. Ceramic: 0.01 μF ±10%, 50 VDCW.	R308	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
C632	19A702052P22	Ceramic: 0.047 µF ±10%, 50 VDCW.	R309	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
C633	19A702052P7	Ceramic: 2200 pF ±10%, 50 VDCW.	R310 and		
C634	19A143565P12	Ceramic: 220000 pF ±10%. 50 VDCW; sim to KE	R311	19B801251P153	Metal film: 15K ohms ±5%, 1/10 w.
C635	19A702061P69	MET C323C224K5R5CA. Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30	R312		
0000	10/11 02 00 11 00	PPM/°C.	thru R314	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
C636 thru			R315	19B801251P683	Metal film: 68K ohms ±5%, 1/10 w.
C638	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30	R316	19B801251P393	Metal film: 39K ohms ±5%, 1/10 w.
		PPM/°C.	*R317 R318	19B801251P393	Metal film: 39K ohms ±5%, 1/10 w.
C639 C640	19A702052P26 19A702052P10	Ceramic: 0.1 µF ±10%, 50 VDCW	R319	19B801251P474 19B801251P683	Metal film: 470K ohms ±5%, 1/10 w. Metal film: 68K ohms ±5%, 1/10 w.
C640 C641	19A702052P10	Ceramic: 4700 pF ±10%, 50 VDCW. Ceramic: 6800 pF ±10%, 50 VDCW.	R320	19B801251P274	Metal film: 270K ohms ±5%, 1/10 w.
C642	19A702236P36	Ceramic: 27 pF $\pm$ 5%, 50 VDCW, temp coef 0 $\pm$ 30	R321	19A705496P7	Variable, surface mount: 100K ohms ±25%, 1/10 w.
		PPM/°C.	R322	19B801251P183	Metal film: 18K ohms ±5%, 1/10 w.
C643 C701	19A702052P134 19A702061P37	Ceramic: 0.1 $\mu$ F ±5%, 25 VDCW.	R324 R325	19B801251P223 19B801251P823	Metal film: 22K ohms ±5%, 1/10 w.
0/01	19A/02001F3/	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0±30 PPM/°C.	R326	19B801251P474	Metal film: 82K ohms ±5%, 1/10 w. Metal film: 470K ohms ±5%, 1/10 w.
C703	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0±30	R327	19B801251P274	Metal film: 270K ohms ±5%, 1/10 w.
C704	19A702061P77	PPM. Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0±30	R328	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
0/04	10/11 02 00 11 11	PPM.	R329	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
C705	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30	R330 R601	19B801251P224 19B801251P273	Metal film: 220K ohms ±5%, 1/10 w. Metal film: 27K ohms ±5%, 1/10 w.
C801	19A705205P2	PPM/°C. Tantalum: 1 μF, 16 VDCW; sim to Sprague 293D.	R602	19B801251P272	Metal film: 2.7K ohms ±5%, 1/10 w.
C804	19A702052P14	Ceramic: $0.01 \ \mu\text{F} \pm 10\%$ , 50 VDCW.	R603	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
C805	19A701534P9	Tantalum: 47 µF ±20%, 6.3 VDCW.	R604	19B801251P472	Metal film: 4.7K ohms ±5%, 1/10 w.
C806	19A704879P5	Electrolytic: $10 \mu\text{F} \pm 20\%$ , $16 \text{VDCW}$ .	R605 R606	19B801251P223 19B801251P473	Metal film: 22K ohms ±5%, 1/10 w. Metal film: 47K ohms ±5%, 1/10 w.
C807 C808	19A705205P14 19A702061P69	Tantalum: 6.8 $\mu$ F, 6 VDCW; sim to Sprague 293D. Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30	R607	19B801251P681	Metal film: 680 ohms ±5%, 1/10 w.
	10/11 02 00 11 00	PPM/°C.	R608	19A705496P6	Resistor, variable surface mount: 50K ohms ±25%,
*C809	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0±30 PPM.			adjustment range 15% to 85%; sim to MURATA Type RGV4E.
			R609		Type nevez.
		DIODES	and R610	19B801251P153	Metal film: 15K ohms ±5%, 1/10 w.
D601	19A705377P3	Silicon, Hot Carrier: sim to HSMS-2920.	R610	19B801251P103	Metal film: 15K onms $\pm$ 5%, 1/10 w. Metal film: 10K ohms $\pm$ 5%, 1/10 w.
D701			R612	19B801251P273	Metal film: 27K ohms $\pm$ 5%, 1/10 w.
thru D705	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.	R613	19B801251P272	Metal film: 2.7K ohms ±5%, 1/10 w.
D707	10/1/0000012		R614	19B801251P153	Metal film: 15K ohms ±5%, 1/10 w.
and D708	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.	R615 R616	19B801251P563 19B801251P473	Metal film: 56K ohms ±5%, 1/10 w. Metal film: 47K ohms ±5%, 1/10 w.
D709	13/10003312	Sincon. 2 Diodes in Genes, sin to DAV35.	R617	19B801251P333	Metal film: 33K ohms ±5%, 1/10 w.
thru D711	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.	R618	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
D801	19A116585P1	Silicon, fast recovery, 600 mA, 50 PIV.	R619	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
			R620 R621	19B801251P103 19B801251P562	Metal film: 10K ohms ±5%, 1/10 w. Metal film: 5.6K ohms ±5%, 1/10 w.
		JACKS	R622	19B801251P222	Metal film: 2.2K ohms ±5%, 1/10 w.
J701		Part of printed wire board 19d902631P1.	R623	19B801251P473	Metal film: $47K$ ohms $\pm 5\%$ , $1/10$ w.
J801	19A705482P1	Printed wire, 2-part; sim to SAMTEC SSW-112-01- SS.	R624	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
J802	19B209648P1	Contact, electrical.	R625	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
J901		Part of printed wire board.	R626 R627	19B801251P471 19B801251P472	Metal film: 470 ohms ±5%, 1/10 w. Metal film: 4.7K ohms ±5%, 1/10 w.
			R628	19B801251P823	Metal film: $82K$ ohms $\pm 5\%$ , $1/10$ w.
		INDUCTORS	R629	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
L301	344A3289P17	Fixed coil; 1 μH +5%. Sim to TDK NL252018T- 1ROJ.	R630	19B801251P472	Metal film: 4.7K ohms ±5%, 1/10 w.

# PARTS LIST

SYMBOL	PART NO.	DESCRIPTION
R631	19B801251P824	Metal film: 820K ohms $\pm$ 5%, 1/10 w.
*R632	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R633	19B801251P821 19B801251P272	Metal film: 820 ohms ±5%, 1/10 w.
R634 R635	19B801251P272 19B801251P822	Metal film: 2.7K ohms ±5%, 1/10 w. Metal film: 8.2K ohms ±5%, 1/10 w.
R636	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R637	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R638	19B801251P823	Metal film: 82K ohms ±5%, 1/10 w.
R639	19B801251P154	Metal film: 150K ohms ±5%, 1/10 w.
R640	19B801251P274	Metal film: 270K ohms ±5%, 1/10 w.
R641 R642	19B801251P473 19B801251P102	Metal film: 47K ohms ±5%, 1/10 w. Metal film: 1K ohms ±5%, 1/10 w.
R643	19B801251P102	Metal film: 100K ohms $\pm 5\%$ , 1/10 w.
R644	19B801251P123	Metal film: 12K ohms ±5%, 1/10 w.
R645	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R646		
thru R649	19B801251P100	Metal film: 10 ohms ±5%, 1/10 w.
R650	19B801251P154	Metal film: 150K ohms ±5%, 1/10 w.
R651	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R652		
and R653	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
R654	19B801251P682	Metal film: 6.8K ohms ±5%, 1/10 w.
R655		
and R656	19B801251P474	Metal film: 470K ohms ±5%, 1/10 w.
R657	19B801251P473	Metal film: $470000000 \pm 5\%$ , $1/10$ w.
R658	19B801251P333	Metal film: 33K ohms $\pm$ 5%, 1/10 w.
R659	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R660	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R661 R662	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
and		
R663	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R664	19A705813P1	Thermistor: sim to AL03006-624-73-G100.
R665 R666	19B801251P124 19B801251P104	Metal film: 120K ohms ±5%, 1/10 w. Metal film: 100K ohms ±5%, 1/10 w.
R667	19B801251P473	Metal film: 47K ohms $\pm$ 5%, 1/10 w.
R668		
and	1000010510000	Matal films 22K above 15% 1/10 vs
R669 R670	19B801251P333 19B801251P563	Metal film: 33K ohms ±5%, 1/10 w. Metal film: 56K ohms ±5%, 1/10 w.
R671	19B801251P222	Metal film: 2.2K ohms $\pm 5\%$ , 1/10 w.
R672	19B801251P561	Metal film: 560 ohms ±5%, 1/10 w.
R673	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
R674	19B801251P684	Metal film: 680K ohms ±5%, 1/10 w.
*R675	REP624656/422	Metal film: 422K ohms ±1%, 1/10 w.
*R676 R677	REP624656/39 19B801251P334	Metal film: 390K ohms ±1%, 1/10 w. Metal film: 330K ohms ±5%, 1/10 w.
R678	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R679	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
R701		
thru R704	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R705	19B801251P103	Metal film: 100K of $\pm 5\%$ , 1/10 w.
R706	19B801251P104	Metal film: 100K ohms $\pm$ 5%, 1/10 w.
R712	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R715 thru		
R719	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R720	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R721	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R722 R723	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
thru		
R725	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R726	19B801251P824	Metal film: 820K ohms ±5%, 1/10 w.
R727 R728	19B801251P394 19B801251P224	Metal film: 390K ohms ±5%, 1/10 w. Metal film: 220K ohms ±5%, 1/10 w.
R728	19B801251P224	Metal film: 220K onms $\pm$ 5%, 1/10 w. Metal film: 100K ohms $\pm$ 5%, 1/10 w.
R730	19A702931P234	Metal film: 2210 ohms ±1%, 200 VDCW, 1/8 w.
R731	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R732	19B801251P333	Metal film: 33K ohms ±5%, 1/10 w.
R733	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R734 thru		
R736	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R737	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R738	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R739 R801	19B801251P472 19B801251P223	Metal film: 4.7K ohms ±5%, 1/10 w.
R801 R802	19B801251P223 19B801251P183	Metal film: 22K ohms ±5%, 1/10 w. Metal film: 18K ohms ±5%, 1/10 w.
R803	19B801251P222	Metal film: 2.2K ohms $\pm 5\%$ , 1/10 w.
R804		
and R805	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.

# LBI-38975

SYMBOL	PART NO.	DESCRIPTION
R806 R807 R808 R809	19B801251P473 19B801251P472 19B801251P104 19B801251P333	Metal film: 47K ohms ±5%, 1/10 w. Metal film: 4.7K ohms ±5%, 1/10 w. Metal film: 100K ohms ±5%, 1/10 w. Metal film: 33K ohms ±5%, 1/10 w.
R810	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
U301 U302 and U303	19A705450P2 19A702293P3	Dual Operational Amplifier, sim to MC34072. Linear: Dual Op Amp; sim to LM358D.
U601 U602 U603	19A702293P1 19A702293P3 19A702705P3	Linear: Quad Op Amp; sim to LM324D. Linear: Dual Op Amp; sim to LM358D. Digital: 8-Channel Analog Multiplexer; sim to 4051BM.
U604 U605	19A705452P1 19A702705P4	Linear: Audio Amplifier; sim to TDA 2822M. Digital: Quad Analog Switch/Multiplexer; sim to 4066BM.
U606 U701 U801 U802 U803 U804	19A702293P3 RYT1186070/1 19A705454P1 19A702536P1 19A703987P322 RYT1186063/1	Linear: Dual Op Amp; sim to LM358D. EEPROM: CMOS. Voltage Detector, sim to Seiko S 8054ALO. Binear positive voltage regulator; sim to LM2931AZ- 8-bit shift register. Digital: 48-Bit Serial Number ROM.
Y701	19A702511G26	Quartz: 11.0592 MHz.
	19A702364P310 19B801570P2 19A705662P1	MISCELLANEOUS Machine screw, TORX Drive: No. M3-0.5 x 10. Connector holder. Connector, Elastomeric.
A3		FRONT CAP ASSEMBLY (CONVENTIONAL) 19D902180G10 (CONVENTIONAL/DTMF) 19D902180G11
B902	19A149673P1	MODULE Round: Water Proof, 50 ohms, 1/2 w.; sim to Line Electric Co. VS-50W24.
	19A702364P1305 19C851997P1 19C851636P2 19A705777P1	MISCELLANEOUS Machine screw. Gasket, Speaker. Switch pad. Nameplate.
		FRONT COVER ASSEMBLY (CONVENTIONAL) 19D902072G17
	19C852455P1 19A116318P4 19A705664P1 344A4654P1 19B801566P8 344A3087P11 19D902072P41	Board, SCAN Foil, Magnetic shielding: 1.5 inches long Gasket Gasket Shield Cable Keypad
		FRONT COVER ASSEMBLY (CONVENTIONAL/DTMF)
Y1	19A702511G26 19D902072P3 19A116318P4 19A705664P1 19A702364P304 19C851992G1 344A4654P1 344A4054P1	19D902072G18 Crystal Unit. Keypad, DTMF. Foil, Magnetic shielding: 1.5 inches long. Gasket. Machine screw. Board, SCAN/DTMF. Gasket. Cable.
		LCD ASSEMBLY 19A705090G6
H1	19C851660P2	Display crystal.

SYMBOL	PART NO.	DESCRIPTION
		MICOLUMNEOUD
	19A703685P3 19B801569P1 19C851719P2	MISCELLANEOUS LCD connector. Diffuser. Lens.
		CONTROL ASSEMBLY 19A705090G10
00		······CAPACITORS ······
C3 thru C7	19A702052P3	Ceramic: 470 pF ±10%, 50 VDCW.
J1	19A115834P1	Contact, electrical: sim to AMP 2-330808-8.
M1	19A701301P3	METERS Cartridge: Electret.
S1 S2	19A705712P1 19A705712P2	Subminiature switch.
29 32	19A705733P4 19B801571P2	MISCELLANEOUS Contact frame, circuitized.
32 36	196801571P2 19C851722P1	Dome switch. Auxiliary boot jack.
		CONVENTIONAL/DTMF BOARD 19C851992G1
		CAPACITORS
C1	19A705205P206	Tantalum: 10.0 μF ±20%, 16 VDCW.
C2 C3	19A705205P223 19A702052P6	Tantalum: 22 $\mu$ F, 6 VDCW; sim to Sprague 293D. Ceramic: 1500 pF ±10%, 50 VDCW.
C4	19A702052P14	Ceramic: 0.01 µF ±10%, 50 VDCW.
C5 C6	19A702052P3 19A702052P14	Ceramic: 470 pF $\pm$ 10%, 50 VDCW. Ceramic: 0.01 $\mu$ F $\pm$ 10%, 50 VDCW.
C7	19A702052P5	Ceramic: 1000 pF $\pm$ 10%, 50 VDCW.
		DIODES
D1	19A702526P2	Silicon: Schottky Barrier; sim to BAT 17.
		JACKS
J802		Part of printed wire board.
		TRANSISTORS
Q1 Q2	19A134739P2	Silicon, NPN.
and Q3 Q4	19A700076P2 19A700059P2	Silicon, NPN: sim to MMBT3904, low profile. Silicon, PNP: sim to MMBT3906, low profile.
		RESISTORS
R2 R3	19A149818P473 19A149818P104	Metal film: 47K ohms $\pm$ 5%, 1/16 w. Metal film: 100K ohms $\pm$ 5%, 1/16 w.
R4 R5	19A149818P822	Metal film: 8.2K ohms $\pm$ 5%, 1/16 w.
thru R8	19A149818P103	Metal film: 10K ohms ±5%, 1/16 w.
R9	19A149818P223	Metal film: 22K ohms $\pm 5\%$ , 1/16 w.
R10	19A149818P393	Metal film: 39K ohms ±5%, 1/16 w.
R11 R12	19A149818P823 19A149818P154	Metal film: 82K ohms ±5%, 1/16 w. Metal film: 150K ohms ±5%, 1/16 w.
R13	19A149818P153	Metal film: 15K ohms ±5%, 1/16 w.
R14 R15	19A149818P223	Metal film: 22K ohms ±5%, 1/16 w.
and R16	19A149818P333	Metal film: 33K ohms ±5%, 1/16 w.
R17 R18	19A149818P103 19A149818P224	Metal film: 10K ohms $\pm$ 5%, 1/16 w. Metal film: 220K ohms $\pm$ 5%, 1/16 w.
R19	19A149818P224	Metal film: 10K ohms $\pm$ 5%, 1/16 w.
R20	19A149818P392	Metal film: 3.9K ohms ±5%, 1/16 w.
R21 R22	19A149818P103 19A149818P273	Metal film: 10K ohms $\pm$ 5%, 1/16 w. Metal film: 27K ohms $\pm$ 5%, 1/16 w.
R23	19A149818P562	Metal film: 5.6K ohms $\pm$ 5%, 1/16 w.
	- I	

#### SYMBOL PART NO. DESCRIPTION ----- INTEGRATED CIRCUITS -----U1 19A704345P30 Integrated circuit, Digital CHMOS: 8-bit micro procssor. ----- CRYSTALS ------Y1 19A702511G26 Quartz: 11.0592 MHz. LCD DRIVER BOARD 19C851720G1 ----- CAPACITORS 19A702052P6 Ceramic: 1500 pF ±10%, 50 VDCW. C1 C2 19A702052P26 Ceramic: 0.1 µF ±10%, 50 VDCW ----- DIODES -----D1 thru D4 19A705713P1 LED, Subminiature. ----- JACKS -----J2 Part of printed wire board. ----- PLUGS -----P1 19B801235P13 Electrical contact. P2 19B801235P3 Electrical contact. ----- TRANSISTORS -----19A700059P2 Silicon, PNP: sim to MMBT3906, low profile. Q1 Q2 19A700076P2 Silicon, NPN: sim to MMBT3904, low profile. ----- RESISTORS ------R1 19B801251P105 Metal film: 1M ohms +5% 1/10 w R2 19B801251P221 Metal film: 220 ohms ±5%, 1/10 w. R3 and R4 19B801251P124 Metal film: 120K ohms ±5%, 1/10 w. R5 and R6 19B801251P472 Metal film: 4.7K ohms ±5%, 1/10 w. R7 19B801251P221 Metal film: 220 ohms ±5%, 1/10 w. ----- INTEGRATED CIRCUITS -----U1 19A705714P1 LCD driver chip. ----- MISCELLANEOUS ------19C851720G7 LCD driver. Δ

#### PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter" which is stamped after the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for the descriptions of parts affected by these revisions.

#### REV. A - SPUR FILTER BOARD 19C851678G4

To correct response to serial number U1 was 349A9595G1.

REV. B - SPUR FILTER BOARD 19C851678G4

To correct DCG inversion on UHF band in talkaround and correct incorrect channel number in display when scanning P1 channel. U1 was 349A9595G2.

#### REV. A - SCAN/DTMF BOARD 19C851992G1

To correct speaker popping problem when CG is disabled. R13 was 56 ohm (19A149818P563). R20 was 10K ohm (19A149818P103). R21 added; 10ohm (19A149818P103). R22 added; 27K ohm (19A149818P273). R23 added; 5.6K ohm (19A149818P562). Q3 added; NPN (19A700076P2). Q4 added; PNP (19A700059P2).

# PARTS LIST

#### REV. C - SPUR FILTER BOARD 19C851678G4

Wrong channel number displayed when scanning and CG was disabled with monitor button and selected channel was P1 or P2. U1 was 349A9595G3.

#### REV. D - SPUR FILTER BOARD 19C851678G4

Radio occasionally unmutes on noise when unkeying. U1 was 349A9595G4.

#### REV. A - AUDIO/LOGIC BOARD 19D902631G2

To prevent RF getting into low voltage detector circuit. C809 added.

#### REV. B - AUDIO/LOGIC BOARD 19D902631G2

To make CG frequency response constant across band.

R675 was 470K, 5% (19B801251P474).

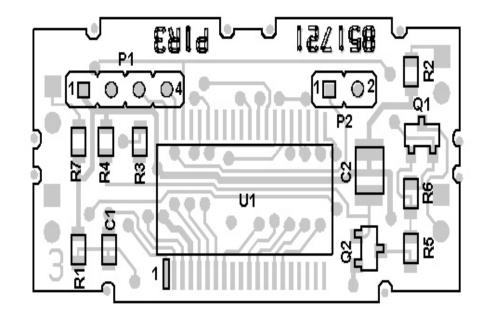
R676 was 390K, 5% (19B801251P394) R317 was 56K (19B801251P563).

To meet EIA standards for receiver frequency response. C615 was 4700pF (19A702052P10).

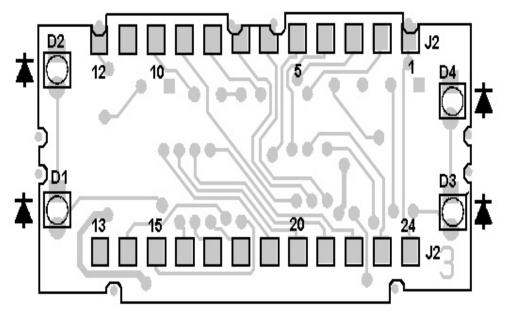
R632 was 150K (19B801251P154).

# **OUTLINE DIAGRAM**

# **COMPONENT SIDE**



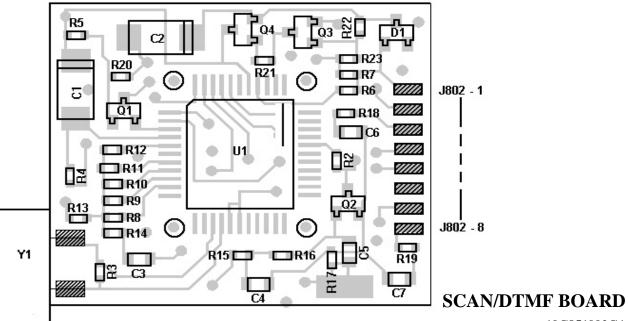
**SOLDER SIDE** 



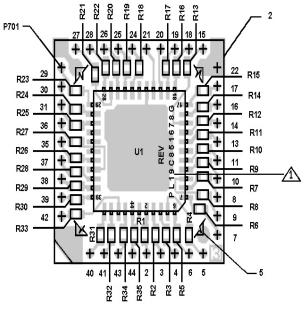
LEAD IDENTIFICATION FOR Q1, & Q2 (SOT) TRANSISTORS (TOP VIEW)

(B) 2 (E) 1 (E) 1 (C)

# **COMPONENT SIDE**



**COMPONENT SIDE** 



(ORIENTATION UNIMPORTANT)

19C851720G1

(19C851720, Sh. 1, Rev. 3) (19C851721, Component Side, Rev. 3) (19C851721, Solder Side, Rev. 3)

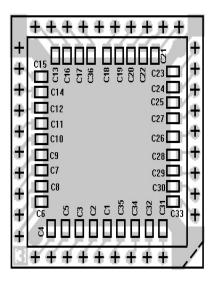
LCD BOARD

# LBI-38975

# 19C851992G1

(19C851992, Sh. 1, Rev. 2) (19C851991, Layer 1, Rev. 2)

# **SOLDER SIDE**



# **SPUR FILTER BOARD**

#### 19C851678G4

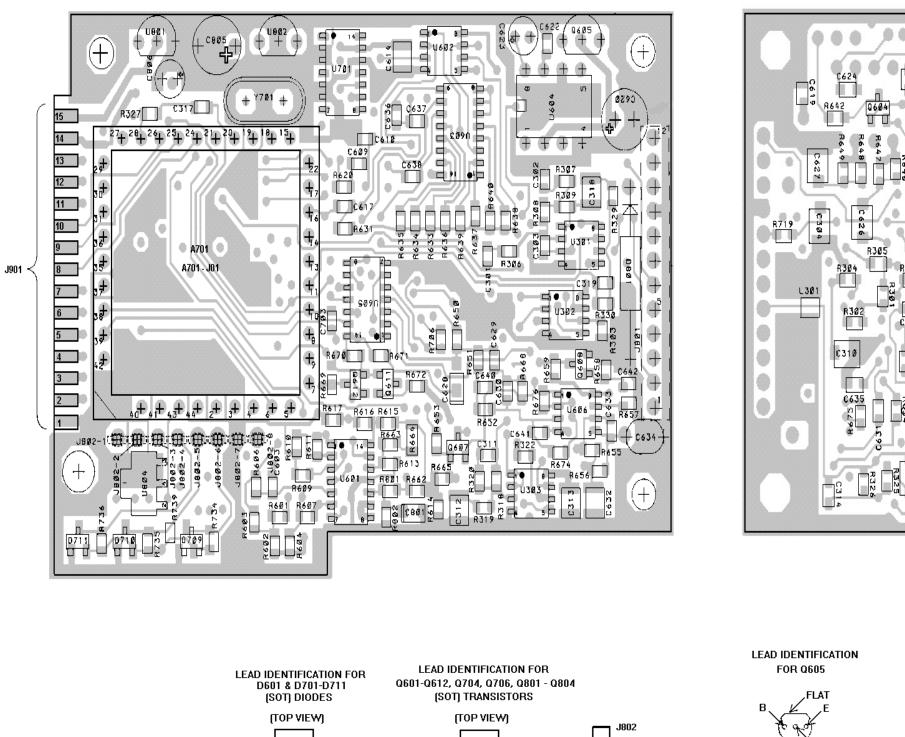
(19C851678, Rev. 1)

(19C851679, Comp. Side, Rev. 3)

(19C851679, Solder Side, Rev. 3)

# **OUTLINE DIAGRAM**

# **SOLDER SIDE**



B **+** 

E **+** 

+ C

**COMPONENT SIDE** 

# **AUDIO/LOGIC BOARD**

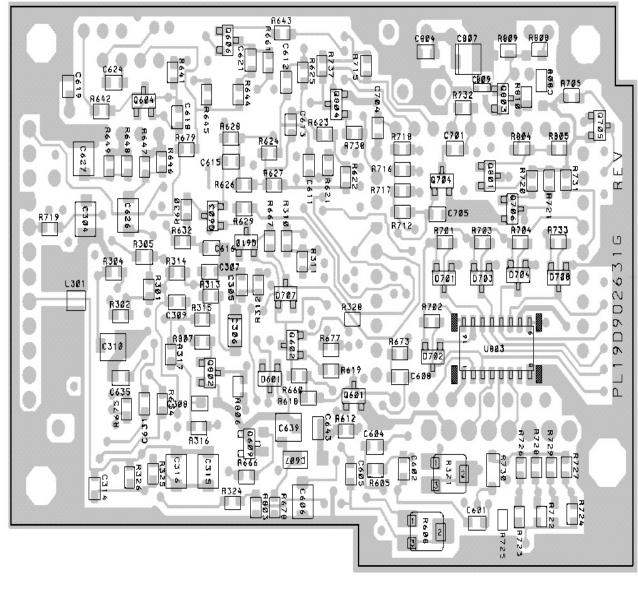
2 +

1 +

+3

19D902631G2

(19D902631, Rev. 2) (19D902632, Layer 1, Rev. 1) (19D902632, Layer 4, Rev. 1)



NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

IN-LINE

TOP VIEW

CPNT SIDE

LEAD IDENTIFICATION FOR U802



IN-LINE TOP VIEW

NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

#### LEAD IDENTIFICATION FOR U801

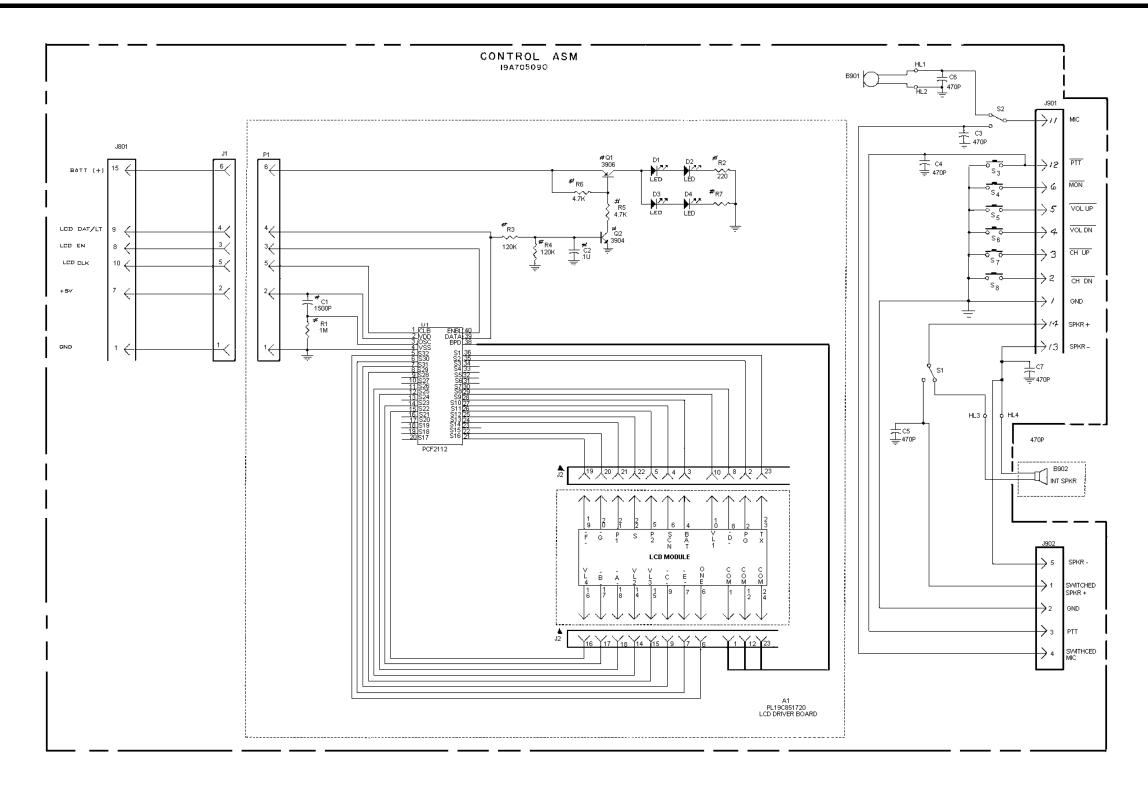


IN-LINE

## TOP VIEW

NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

SCHEMATIC DIAGRAM

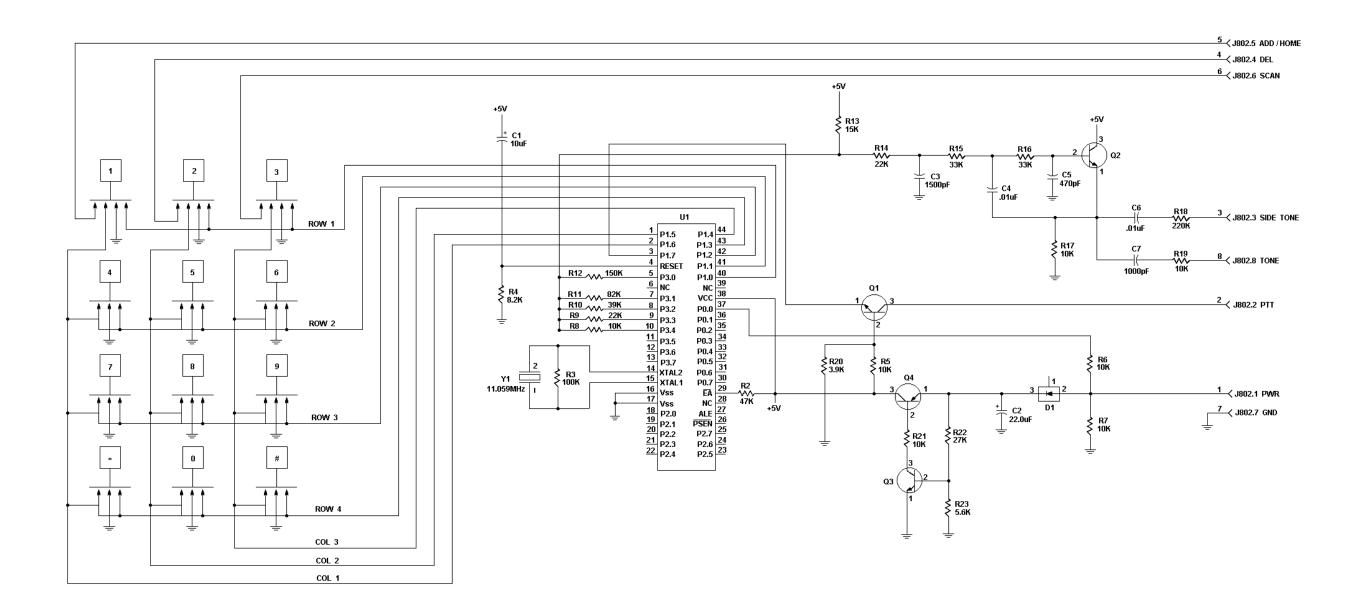


# LBI-38975

# FRONT CAP ASSEMBLY

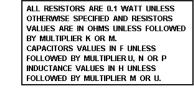
### 19D902180G10 & G11

(19D902216, SH. 1, REV. 0)

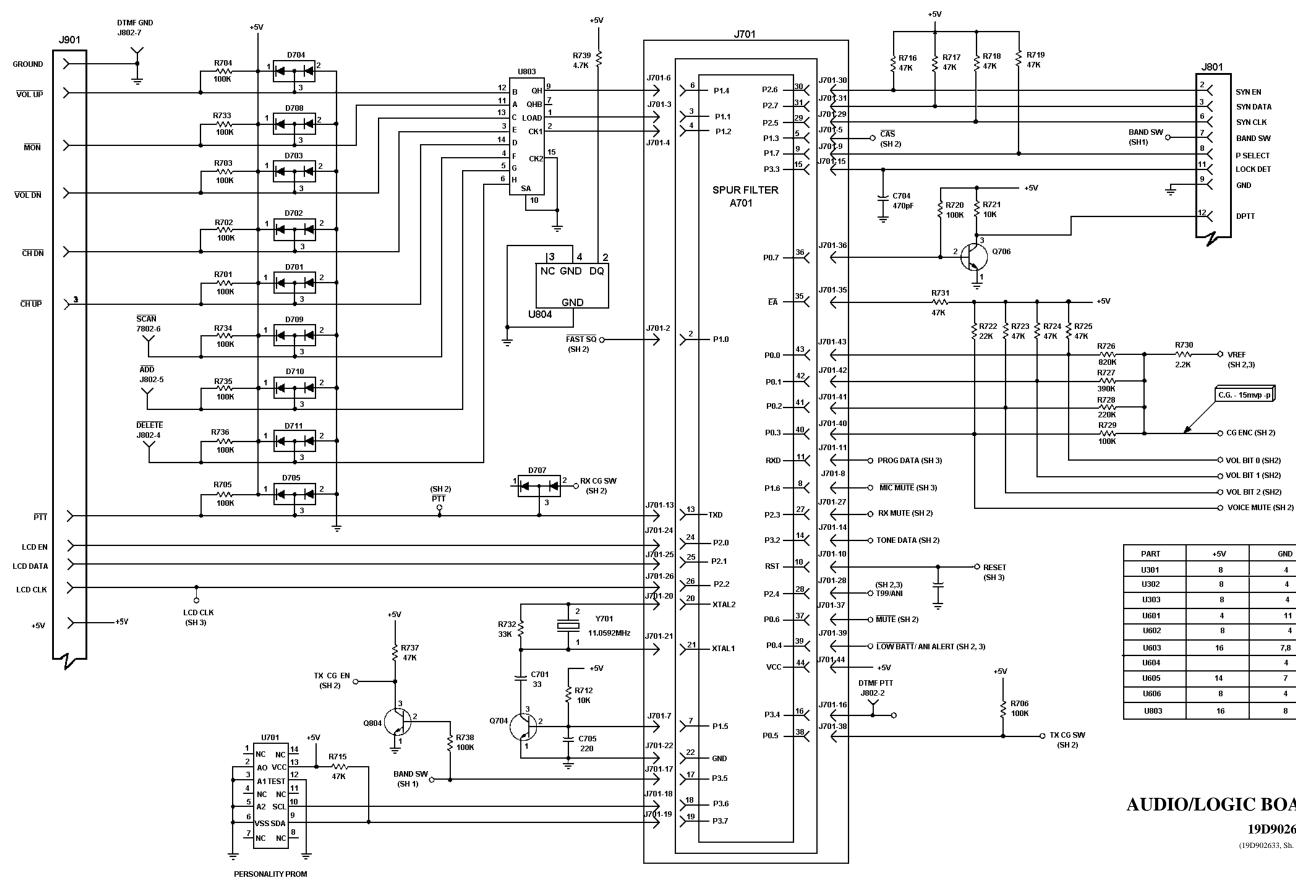


# **SCAN/DTMF BOARD**

**19C851992G1** (19D902999, Sh. 1, Rev. 3)



THIS SCHEMATIC DIAGRAM APPLIES TO MODEL NO. REV LETTER PL19C851992G1 SCHEMATIC DIAGRAM



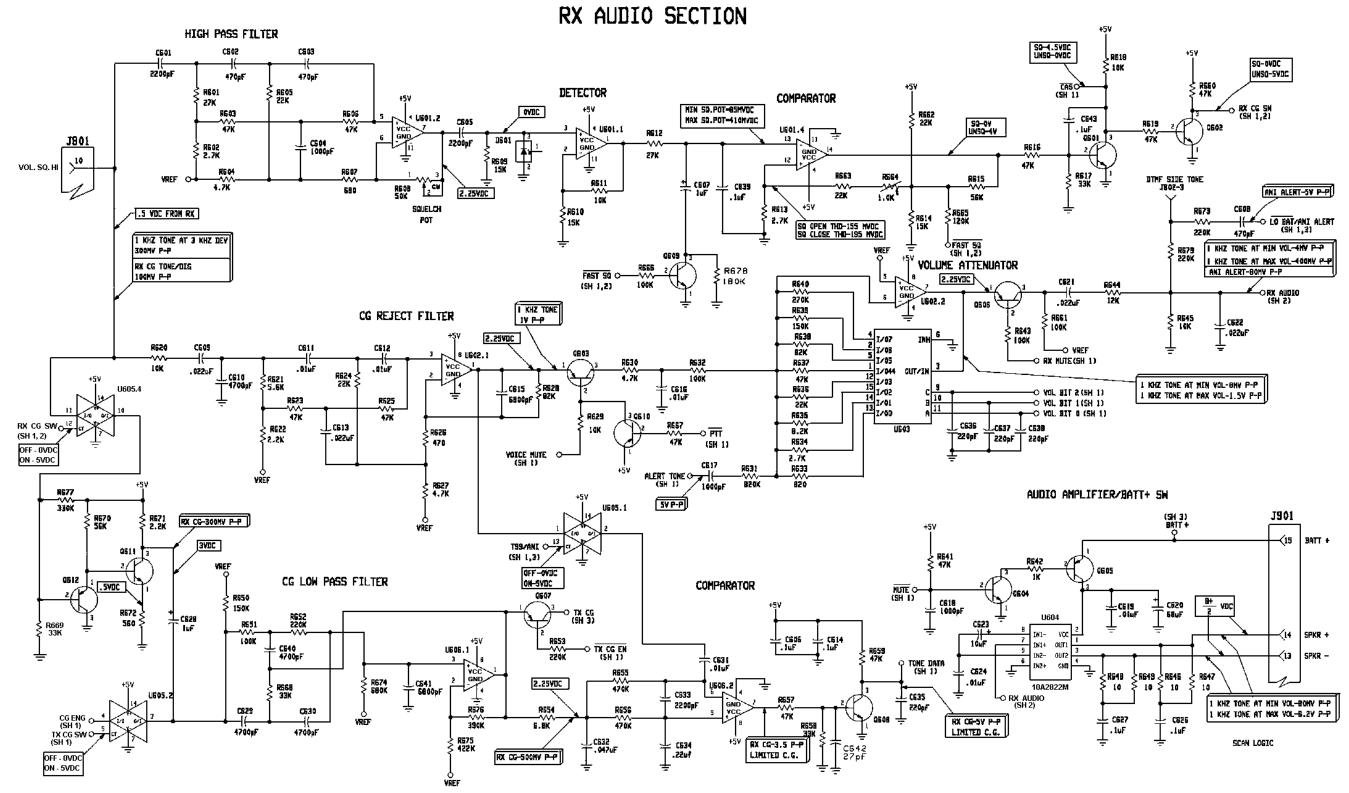
# LBI-38975

PART	+5∨	GND
U301	8	4
U302	8	4
U303	8	4
U601	4	11
U602	8	4
U603	16	7,8
U604		4
U605	14	7
U606	8	4
U803	16	8

# **AUDIO/LOGIC BOARD**

#### 19D902631G2

(19D902633, Sh. 1, Rev. 6)



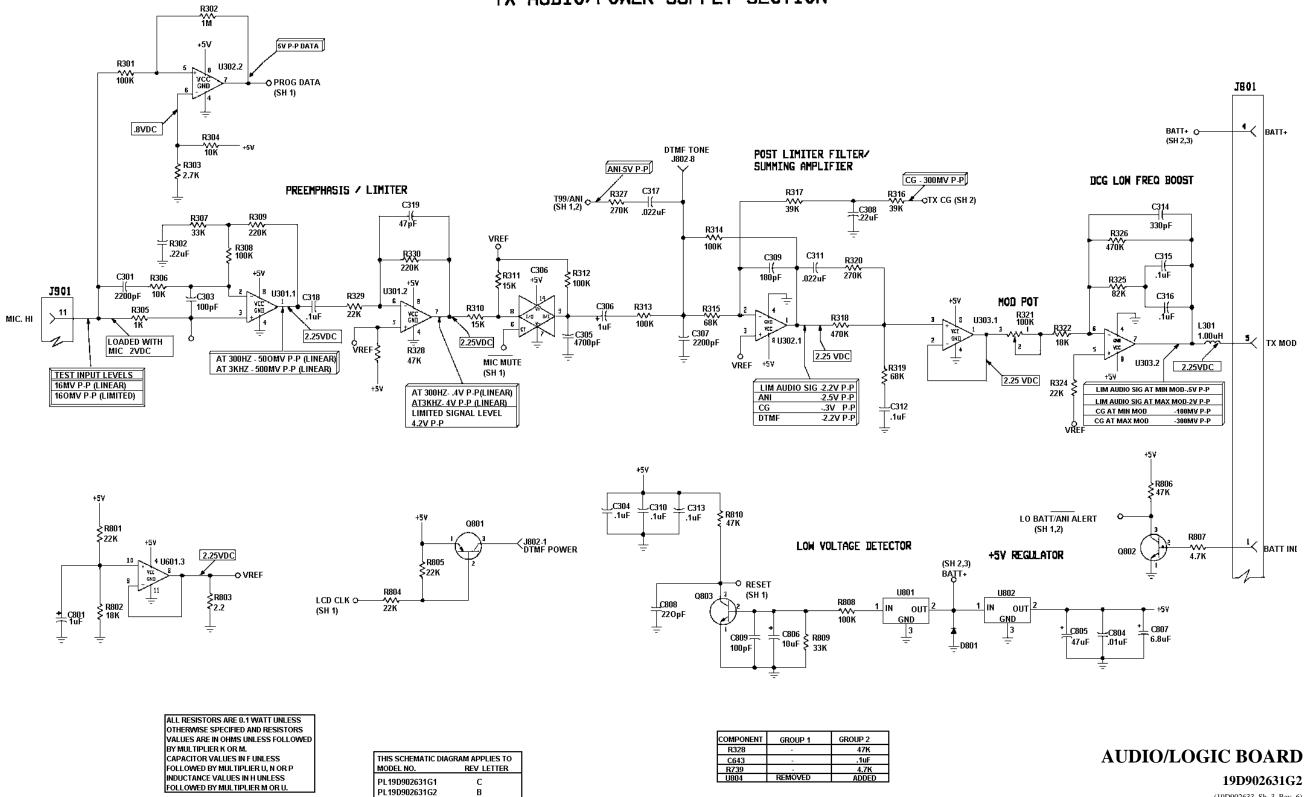
# AUDIO/LOGIC BOARD

#### 19D902631G2

(19D902633, Sh. 2, Rev. 6)

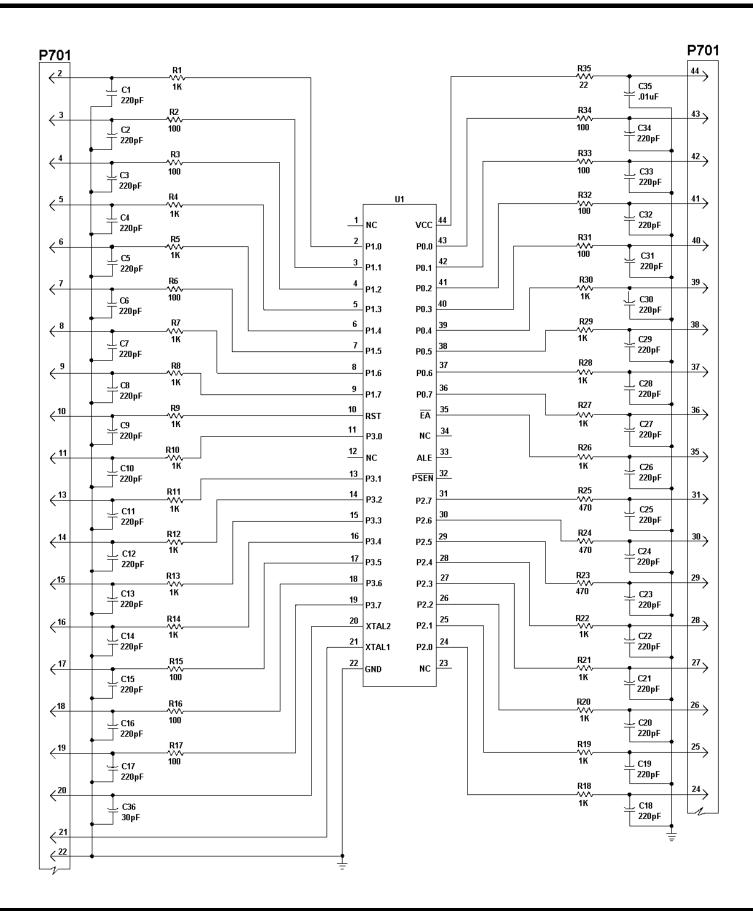
# SCHEMATIC DIAGRAM





# LBI-38975

(19D902633, Sh. 3, Rev. 6)



# **SPUR FILTER BOARD**

**19C851678G4** (19D902215, Rev. 10)

#### ALL RESISTORS ARE 0.1 VATT UNLESS OTHERVISE SPECIFIED AND RESISTORS YALUES ARE IN OHMS UNLESS FOLLOVED BY MULTIPLIER K OR M. CAPACITOR YALUES IN F UNLESS FOLLOVED BY MULTIPLIER U,M, OR P INDUCTANCE YALUES IN H UNLESS FOLLOVED BY MULTIPLIER M OR U.

#### THIS SCHEMATIC DIAGRAM APPLIES TO MODEL NO. REV LETTER

19C851678G1	С
19C851678G2	С
19C851678G3	в
19C851678G4	D

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# LBI-38975